Ternary Volatile Random Access Memory based on Heterogeneous Graphene-CMOS Fabric

- **Santosh Khasanvis**, K. M. Masum Habib*, Mostafizur Rahman, Pritish Narayanan, Roger K. Lake* and Csaba Andras Moritz

> University of Massachusetts Amherst *University of California Riverside





Electrical and Computer Engineering

Outline

- Motivation
- Bi-Layer xGNR Device, Latch
- Proposed Memory Cell Ternary GNTRAM
- Evaluation and Comparison with CMOS SRAM
- Summary

Multistate Memory: Motivation & Vision



Source: 2012 ISSCC Tech Trends

Vision – New multi-bit per cell volatile memory with graphene

Challenges with CMOS SRAM

- Slowdown in area scaling (50% down to 30% per generation)
- Increasing leakage concerns

Concept



Current: Single bit/cell

Proposed: Multi-bit/cell with novel graphene structures

Bi-Layer Graphene Nanoribbon Crossbar Device (xGNR) & Application



Graphene Nanoribbon Crossbar Resonant Tunneling Diode - *K. M. M. Habib and R. K. Lake*, University of California Riverside

 Armchair Graphene Nano-Ribbons arranged in a crossbar geometry (xGNR) exhibit Negative Differential Resistance (NDR)





- xGNRs in series form a latch with multiple stable states (A, B & C)
- Ternary data represented by state node (SN) voltage: A–Logic 0, B–Logic 1, & C–Logic 2

Graphene Nanoribbon Tunneling RAM (GNTRAM)



• xGNR latch forms the memory core of a RAM cell

SN - State Node

- Memory cell selection, read and write operations performed using access transistors
- Schottky diode and Sleep FET mitigate stand-by power consumption

Ternary GNTRAM Operation



Proposed Physical Implementation – Integration with CMOS



- Heterogeneous integration between CMOS and Graphene for validation and benchmarking
- MOS transistors and metal layers for access and routing
- Schottky contact^{*} enabled by interaction between semiconducting GNR and metal

^{*}X. Guan; et al.; , "Modeling of schottky and ohmic contacts between metal and graphene nanoribbons using extended hückel theory (EHT)-based NEGF method," IEDM 2008.

Methodology & Benchmarking

- HSPICE simulation for concept validation, performance and power evaluation
- 16nm Grid-based design rules used to evaluate GNTRAM area

16nm Design Rules

| 1D Gridded Design | M1, M2 Interconnect | Poly | |
|---------------------------------|------------------------|-----------------|--|
| Pitch (16nm technology node) | 40~60 nm | 60~80 nm | |

C. Bencher, et al.. "Gridded design rule scaling: Taking the CPU toward the 16nm node", Proc. SPIE 7274, 2009

Comparison with 16nm High Performance (HP) CMOS SRAM

| | GNT RAM (Per Cell, 1.585 bits) | GN (P | NT RAM Per Bit) | CMOS 6T Scale SRAM Cell | ed | CMOS Gridded 8T SRAM Cell |
|----------------------------|-----------------------------------|-------------|-----------------------------|----------------------------|------------------------------|------------------------------|
| RAM Cell Area (µm²) | 0.03-0.06 | 0.019-0.038 | | 0.026-0.064 | | 0.034-0.067 |
| Active Power (µW) | 2.1 | 1.31 | | 2.1 | | 2.41 |
| Standby Power (pW) | 22 | 13.9 | | 6152 | | 15552 |
| Performance GNT RAM | | | CMOS 6T Scaled SRAM Cell | | CMOS Gridded 8T SRAM Cell | |
| Read Time (ps) | 9.3 | | 8.8 | | 7.7 | |
| Write Time (ps) | 16.3 | | 18.4 | | 18 | |

Density Benefit (per bit) : Upto 1.77x vs. SRAMs Power Savings (per bit): Upto 1.84x (Active) and 1196x (Leakage) vs. HP SRAMs Performance: Comparable to HP CMOS SRAMs

Summary

- Novel ternary memory (1.5 bits/cell) presented with heterogeneous CMOS-Graphene implementation
- Density and power benefits vs. 16nm CMOS SRAMs with comparable performance
- Next Steps: Increasing number of states/cell a new dimension for scaling
- Possibility of all-graphene fabrics as graphene technology matures

Thank You!

<u>Acknowledgements:</u> Collaboration with Prof. Roger Lake, UC Riverside





